



Material Content Data Sheet



Sales Product Name		TLE4274G V50		Issued		1. August 2018		
MA#		MA001132264						
Package		PG-TO263-3-1		Weight*		1598.64 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.945	0.18	0.18	1842	1842
leadframe	inorganic material	phosphorus	7723-14-0	0.091	0.01		57	
	non noble metal	iron	7439-89-6	0.304	0.02		190	
	non noble metal	copper	7440-50-8	304.026	19.02	19.05	190177	190424
	non noble metal	aluminium	7429-90-5	0.182	0.01	0.01	114	114
wire	non noble metal	aluminium	7429-90-5	0.182	0.01	0.01	114	114
encapsulation	organic material	carbon black	1333-86-4	1.456	0.09		911	
	plastics	epoxy resin	-	66.999	4.19		41910	
	inorganic material	silicondioxide	60676-86-0	659.792	41.28	45.56	412719	455540
leadfinish	non noble metal	tin	7440-31-5	9.657	0.60	0.60	6041	6041
plating	inorganic material	phosphorus	7723-14-0	0.001	0.00		1	
	non noble metal	nickel	7440-02-0	0.228	0.01	0.01	143	144
solder	non noble metal	tin	7440-31-5	0.092	0.01		57	
	noble metal	silver	7440-22-4	0.115	0.01		72	
	non noble metal	lead	7439-92-1	4.377	0.27	0.29	2738	2867
heatspreader	inorganic material	phosphorus	7723-14-0	0.165	0.01		103	
	non noble metal	iron	7439-89-6	0.548	0.03		343	
	non noble metal	copper	7440-50-8	547.666	34.26	34.30	342582	343028
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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